All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{CES}	Zero Gate Voltage Collector Current	V_{GE} = 0V, V_{CE} = 600V				500	µA
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	V_{GE} =15V I_C = 450A	T_j = 25°C		1.4	1.8	V
			T_j = 150°C		1.5		
$V_{GE(th)}$	Gate Threshold Voltage	V_{GE} = V_{CE} , I_C = 2mA		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	V_{GE} = 20V, V_{CE} = 0V				600	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
C_{ies}	Input Capacitance	V_{GE} = 0V V_{CE} = 25V f = 1MHz			37		nF
C_{oes}	Output Capacitance				2.3		
C_{res}	Reverse Transfer Capacitance				1.1		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) V_{GE} = ±15V V_{Bus} = 300V I_C = 450A R_G = 1Ω			130		ns
T_r	Rise Time				55		
$T_{d(off)}$	Turn-off Delay Time				250		
T_f	Fall Time				60		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (150°C) V_{GE} = ±15V V_{Bus} = 300V I_C = 450A R_G = 1Ω			145		ns
T_r	Rise Time				60		
$T_{d(off)}$	Turn-off Delay Time				320		
T_f	Fall Time				80		
E_{on}	Turn on Energy	V_{GE} = ±15V V_{Bus} = 300V I_C = 450A R_G = 1Ω	T_j = 25°C		2.25		mJ
			T_j = 150°C		4.2		
E_{off}	Turn off Energy		T_j = 25°C		12.8		mJ
			T_j = 150°C		15.7		

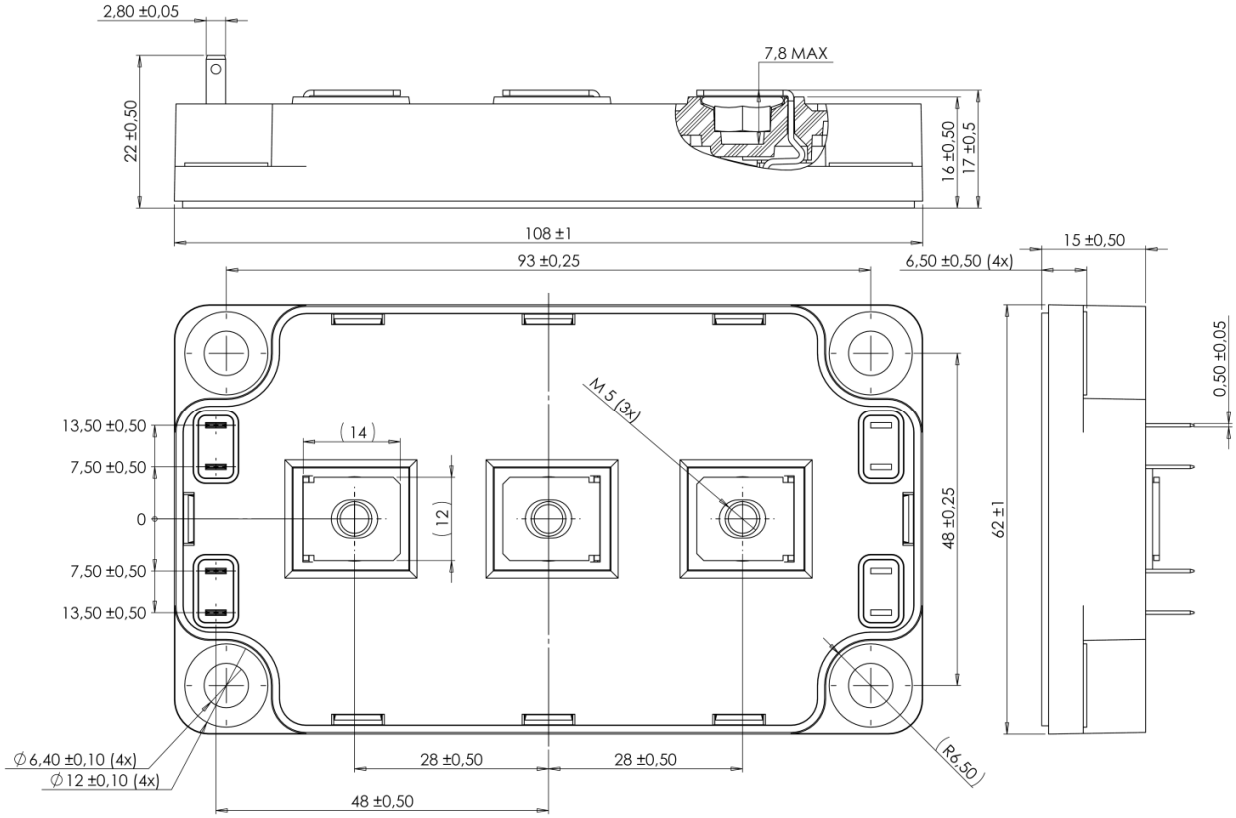
Reverse diode ratings and characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			600			V
I_{RM}	Maximum Reverse Leakage Current	V_R=600V	T_j = 25°C			200	µA
			T_j = 150°C			500	
I_F	DC Forward Current		Tc = 80°C		450		A
V_F	Diode Forward Voltage	I_F = 450A V_{GE} = 0V	T_j = 25°C		1.5	1.9	V
			T_j = 150°C		1.4		
t_{rr}	Reverse Recovery Time	I_F = 450A V_R = 300V di/dt =4000A/µs	T_j = 25°C		120		ns
			T_j = 150°C		210		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		20.3		µC
			T_j = 150°C		42.8		
E_r	Reverse Recovery Energy		T_j = 25°C		5.2		mJ
			T_j = 150°C		10.6		

Thermal and package characteristics

Symbol	*Characteristic*			*Min*	*Typ*	*Max*	*Unit*
R_{thJC}	Junction to Case Thermal Resistance		IGBT			0.085	°C/W
			Diode			0.14	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_J	Operating junction temperature range			-40		175	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	
Wt	Package Weight					300	g

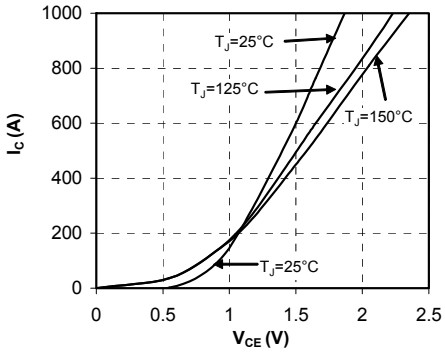
SP6 Package outline (dimensions in mm)



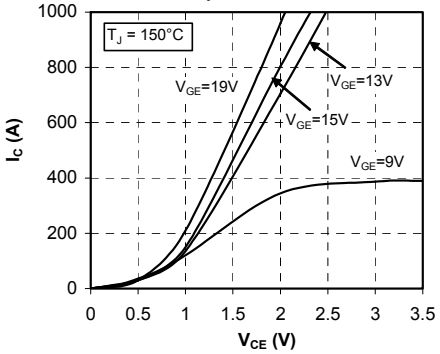
See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

Typical Performance Curve

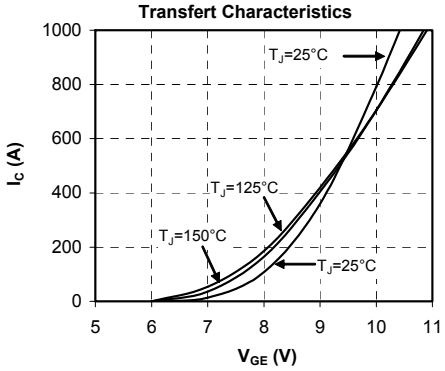
Output Characteristics (V_{GE}=15V)



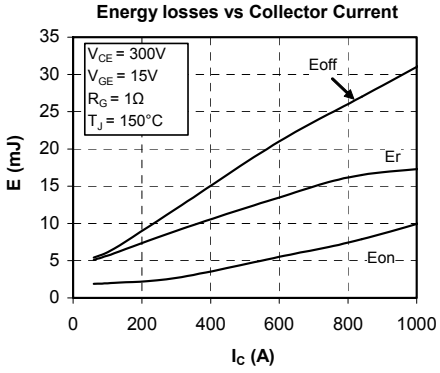
Output Characteristics



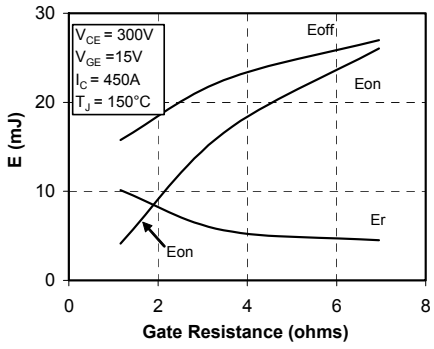
Transfert Characteristics



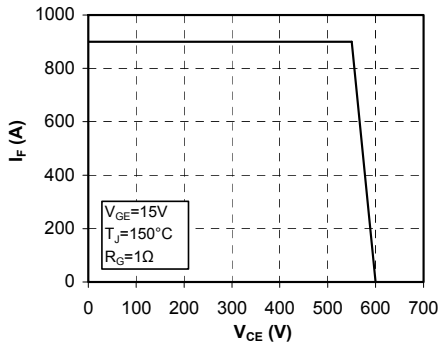
Energy losses vs Collector Current



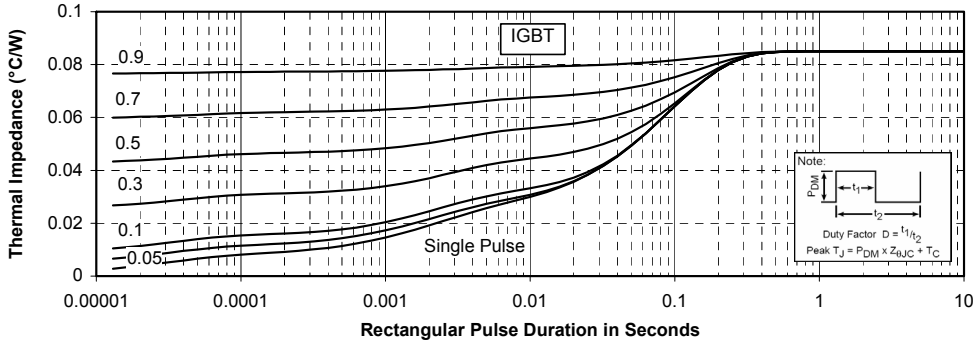
Switching Energy Losses vs Gate Resistance

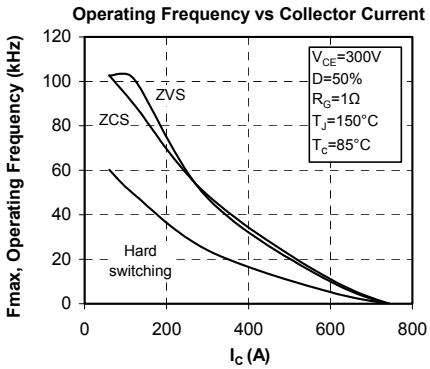


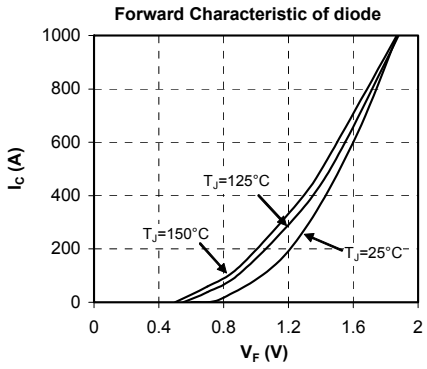
Reverse Bias Safe Operating Area

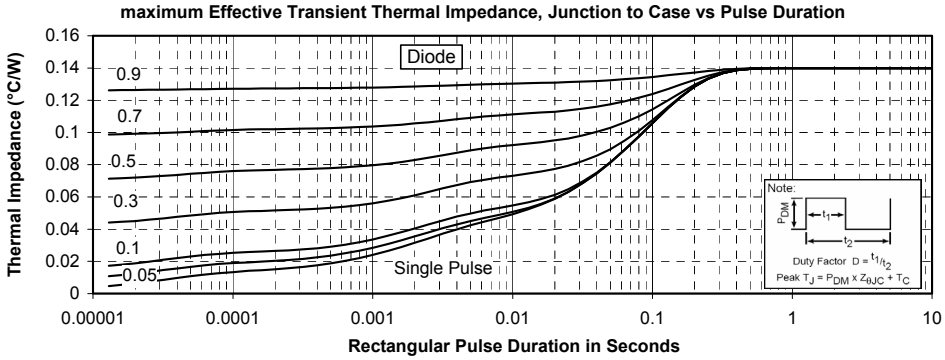


maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration









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